

54F253,74F253

54F253 74F253 Dual 4-Input Multiplexer with TRI-STATE(RM) Outputs



Literature Number: SNOS179A

54F/74F253

Dual 4-Input Multiplexer with TRI-STATE® Outputs

General Description

The 'F253 is a dual 4-input multiplexer with TRI-STATE® outputs. It can select two bits of data from four sources using common select inputs. The output may be individually switched to a high impedance state with a HIGH on the respective Output Enable ($\overline{OE}$) inputs, allowing the outputs to interface directly with bus oriented systems.

Features

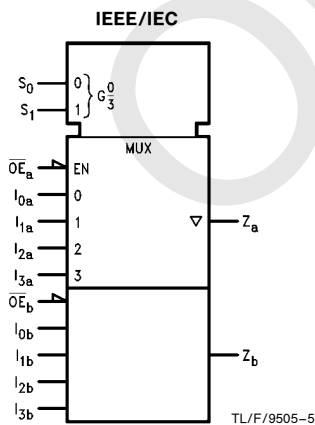
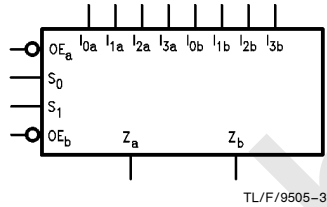
- Multifunction capability
- Non-inverting TRI-STATE outputs
- Guaranteed 4000V minimum ESD protection

Commercial	Military	Package Number	Package Description
74F253PC		N16E	16-Lead (0.300" Wide) Molded Dual-In-Line
	54F253DM (Note 2)	J16A	16-Lead Ceramic Dual-In-Line
74F253SC (Note 1)		M16A	16-Lead (0.150" Wide) Molded Small Outline, JEDEC
74F253SJ (Note 1)		M16D	16-Lead (0.300" Wide) Molded Small Outline, EIAJ
	54F253FM (Note 2)	W16A	16-Lead Cerpack
	54F253LL (Note 2)	E20A	20-Lead Ceramic Leadless Chip Carrier, Type C

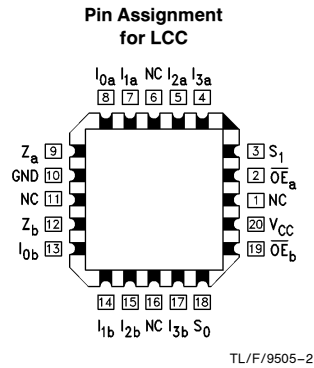
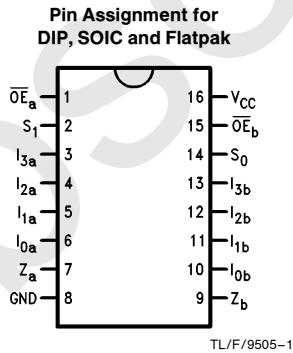
Note 1: Devices also available in 13" reel. Use suffix = SCX and SJX.

Note 2: Military grade device with environmental and burn-in processing. Use suffix = DMQB, FMQB and LMQB.

Logic Symbols



Connection Diagrams



TRI-STATE® is a registered trademark of National Semiconductor Corporation.

Unit Loading/Fan Out

Pin Names	Description	54F/74F	
		U.L. HIGH/LOW	Input I_{IH}/I_{IL} Output I_{OH}/I_{OL}
$I_{0a}-I_{3a}$	Side A Data Inputs	1.0/1.0	20 μ A/ -0.6 mA
$I_{0b}-I_{3b}$	Side B Data Inputs	1.0/1.0	20 μ A/ -0.6 mA
S_0-S_1	Common Select Inputs	1.0/1.0	20 μ A/ -0.6 mA
$\overline{OE}_a$	Side A Output Enable Input (Active LOW)	1.0/1.0	20 μ A/ -0.6 mA
$\overline{OE}_b$	Side B Output Enable Input (Active LOW)	1.0/1.0	20 μ A/ -0.6 mA
Z_a, Z_b	TRI-STATE Outputs	150/40(33.3)	-3 mA/24 mA (20 mA)

Functional Description

This device contains two identical 4-input multiplexers with TRI-STATE outputs. They select two bits from four sources selected by common Select inputs (S_0, S_1). The 4-input multiplexers have individual Output Enable ($\overline{OE}_a, \overline{OE}_b$) inputs which, when HIGH, force the outputs to a high impedance (High Z) state. This device is the logic implementation of a 2-pole, 4-position switch, where the position of the switch is determined by the logic levels supplied to the two select inputs. The logic equations for the outputs are shown below:

$$Z_a = \overline{OE}_a \cdot (I_{0a} \cdot S_1 \cdot \overline{S_0} + I_{1a} \cdot \overline{S_1} \cdot S_0 + I_{2a} \cdot S_1 \cdot \overline{S_0} + I_{3a} \cdot \overline{S_1} \cdot S_0)$$

$$Z_b = \overline{OE}_b \cdot (I_{0b} \cdot S_1 \cdot \overline{S_0} + I_{1b} \cdot \overline{S_1} \cdot S_0 + I_{2b} \cdot S_1 \cdot \overline{S_0} + I_{3b} \cdot \overline{S_1} \cdot S_0)$$

If the outputs of TRI-STATE devices are tied together, all but one device must be in the high impedance state to avoid high currents that would exceed the maximum ratings. Designers should ensure that Output Enable signals to TRI-STATE devices whose outputs are tied together are designed so that there is no overlap.

Truth Table

Select Inputs		Data Inputs				Output Enable	Output
S_0	S_1	I_0	I_1	I_2	I_3	$\overline{OE}$	$\overline{Z}$
X	X	X	X	X	X	H	Z
L	L	L	X	X	X	L	L
L	L	H	X	X	X	L	H
H	L	X	L	X	X	L	L
H	L	X	H	X	X	L	H
L	H	X	X	L	X	L	L
L	H	X	X	H	X	L	H
H	H	X	X	X	L	L	L
H	H	X	X	X	H	L	H

Address inputs S_0 and S_1 are common to both sections.

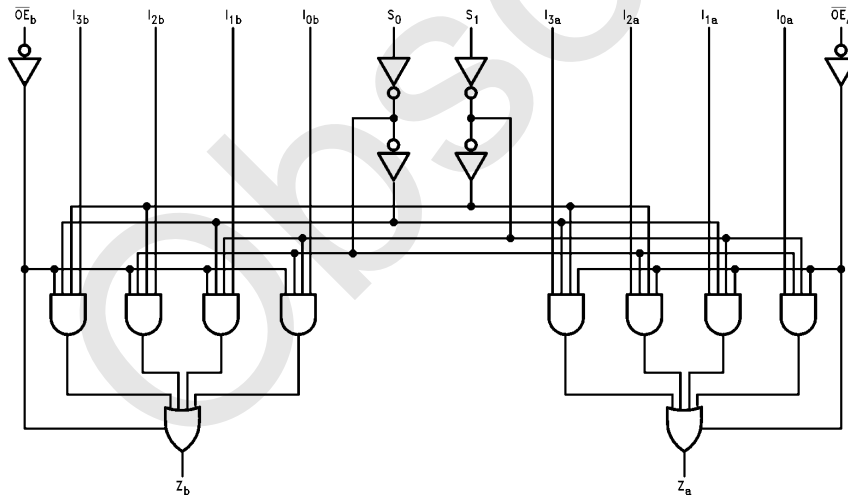
H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

Z = High Impedance

Logic Diagram



TL/F/9505-4

Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Storage Temperature	−65°C to +150°C
Ambient Temperature under Bias	−55°C to +125°C
Junction Temperature under Bias	−55°C to +175°C
Plastic	−55°C to +150°C
V _{CC} Pin Potential to Ground Pin	−0.5V to +7.0V
Input Voltage (Note 2)	−0.5V to +7.0V
Input Current (Note 2)	−30 mA to +5.0 mA
Voltage Applied to Output in HIGH State (with V _{CC} = 0V)	
Standard Output	−0.5V to V _{CC}
TRI-STATE Output	−0.5V to +5.5V

Current Applied to Output in LOW State (Max)

twice the rated I_{OL} (mA)

ESD Last Passing Voltage (Min)

4000V

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

Recommended Operating Conditions

Free Air Ambient Temperature

Military

−55°C to +125°C

Commercial

0°C to +70°C

Supply Voltage

Military

+4.5V to +5.5V

Commercial

+4.5V to +5.5V

DC Electrical Characteristics

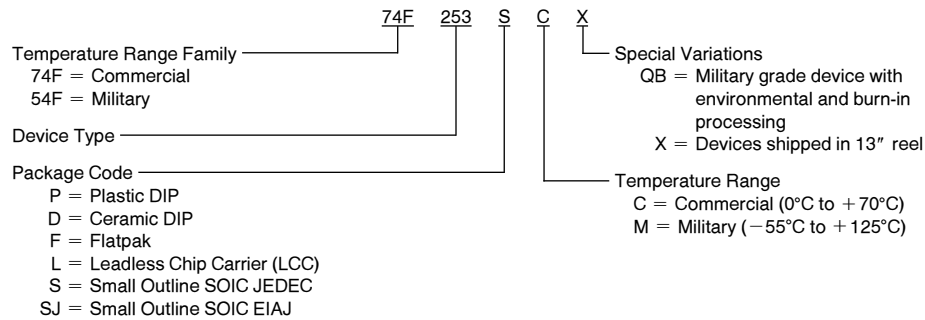
Symbol	Parameter		54F/74F			Units	V _{CC}	Conditions
			Min	Typ	Max			
V _{IH}	Input HIGH Voltage		2.0			V		Recognized as a HIGH Signal
V _{IL}	Input LOW Voltage				0.8	V		Recognized as a LOW Signal
V _{CD}	Input Clamp Diode Voltage				−1.2	V	Min	I _{IN} = −18 mA
V _{OH}	Output HIGH Voltage	54F 10% V _{CC}	2.5			V	Min	I _{OH} = −1 mA
		54F 10% V _{CC}	2.4					I _{OH} = −3 mA
		74F 10% V _{CC}	2.5					I _{OH} = −1 mA
		74F 10% V _{CC}	2.4					I _{OH} = −3 mA
		74F 5% V _{CC}	2.7					I _{OH} = −1 mA
		74F 5% V _{CC}	2.7					I _{OH} = −3 mA
V _{OL}	Output LOW Voltage	54F 10% V _{CC}			0.5	V	Min	I _{OL} = 20 mA
		74F 10% V _{CC}			0.5			I _{OL} = 24 mA
I _{IH}	Input HIGH Current	54F			20.0	μA	Max	V _{IN} = 2.7V
		74F			5.0			
I _{BVI}	Input HIGH Current Breakdown Test	54F			100	μA	Max	V _{IN} = 7.0V
		74F			7.0			
I _{CEX}	Output HIGH Leakage Current	54F			250	μA	Max	V _{OUT} = V _{CC}
		74F			50			
V _{ID}	Input Leakage Test	74F	4.75			V	0.0	I _{ID} = 1.9 μA All Other Pins Grounded
I _{OD}	Output Leakage Circuit Current	74F			3.75	μA	0.0	V _{IOD} = 150 mV All Other Pins Grounded
I _{IL}	Input LOW Current				−0.6	mA	Max	V _{IN} = 0.5V
I _{OZH}	Output Leakage Current				50	μA	Max	V _{OUT} = 2.7V
I _{OZL}	Output Leakage Current				−50	μA	Max	V _{OUT} = 0.5V
I _{OS}	Output Short-Circuit Current		−60 −100		−150 −225	mA	Max	V _{OUT} = 0V V _{OUT} = 0V
I _{ZZ}	Bus Drainage Test				500	μA	0.0V	V _{OUT} = V _{CC}
I _{CCH}	Power Supply Current			11.5	16	mA	Max	V _O = HIGH
I _{CCL}	Power Supply Current			16	23	mA	Max	V _O = LOW
I _{CCZ}	Power Supply Current			16	23	mA	Max	V _O = HIGH Z

AC Electrical Characteristics

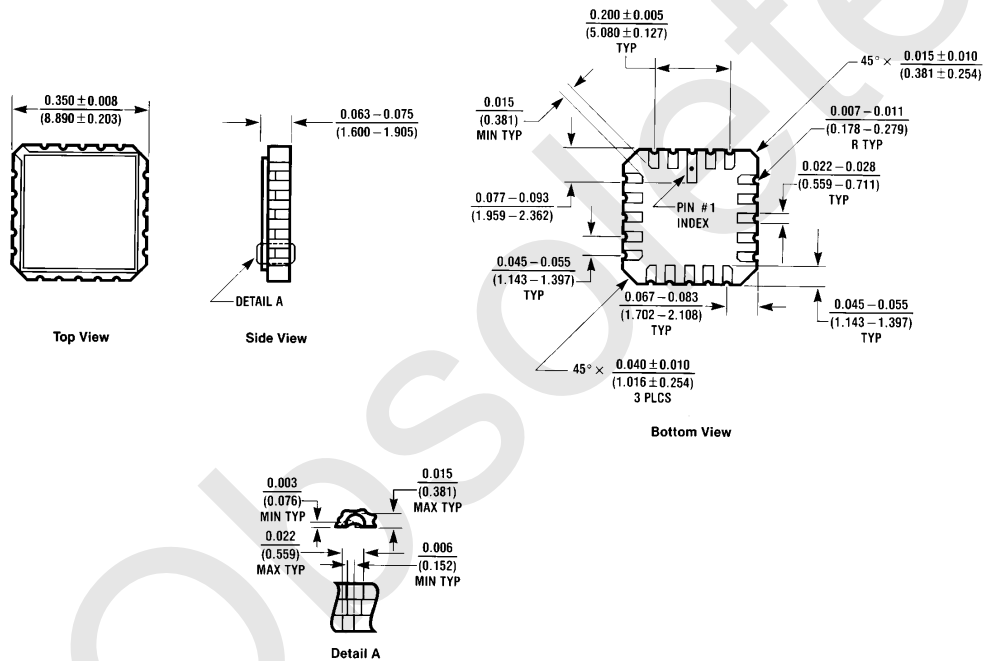
Symbol	Parameter	74F			54F		74F		Units
		T _A = +25°C V _{CC} = +5.0V C _L = 50 pF			T _A , V _{CC} = Mil C _L = 50 pF		T _A , V _{CC} = Com C _L = 50 pF		
		Min	Typ	Max	Min	Max	Min	Max	
t _{PLH} t _{PHL}	Propagation Delay S _n to Z _n	4.5 3.0	8.5 6.5	11.5 9.0	3.5 2.5	15.0 11.0	4.5 3.0	13.0 10.0	ns
t _{PLH} t _{PHL}	Propagation Delay I _n to Z _n	3.0 2.5	5.5 4.5	7.0 6.0	2.5 2.5	9.0 8.0	3.0 2.5	8.0 7.0	ns
t _{PZH} t _{PZL}	Output Enable Time	3.0 3.0	6.0 6.0	8.0 8.0	2.5 2.5	10.0 10.0	3.0 3.0	9.0 9.0	ns
t _{PHZ} t _{PLZ}	Output Disable Time	2.0 2.0	3.7 4.4	5.0 6.0	2.0 2.0	6.5 8.0	2.0 2.0	6.0 7.0	

Ordering Information

The device number is used to form part of a simplified purchasing code where the package type and temperature range are defined as follows:



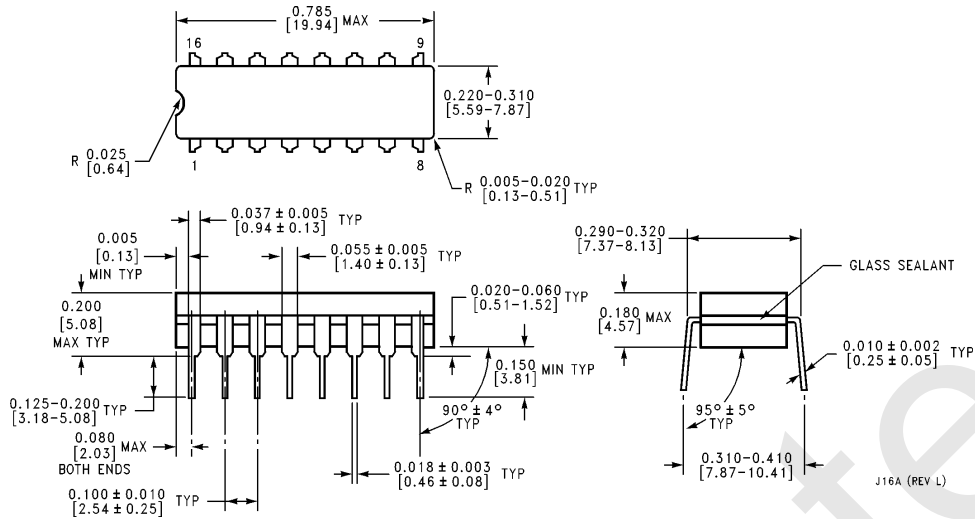
Physical Dimensions inches (millimeters)



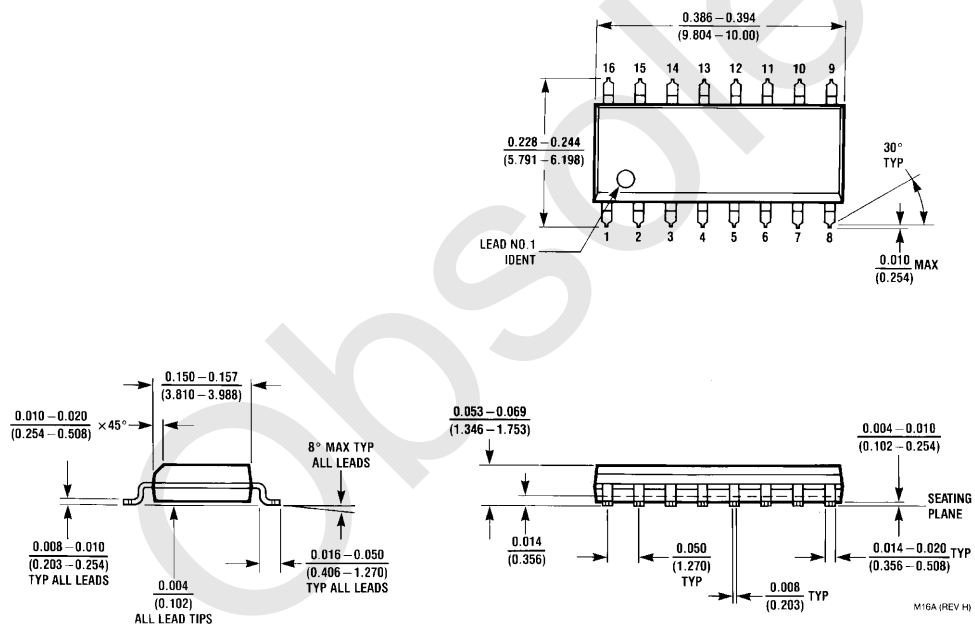
**20-Lead Ceramic Leadless Chip Carrier (L)
NS Package Number E20A**

E20A (REV D)

Physical Dimensions inches (millimeters) (Continued)

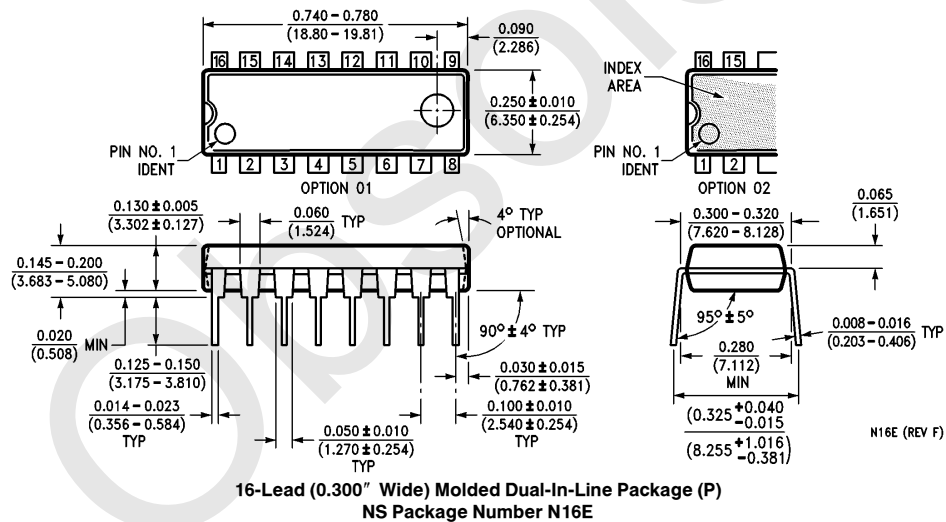
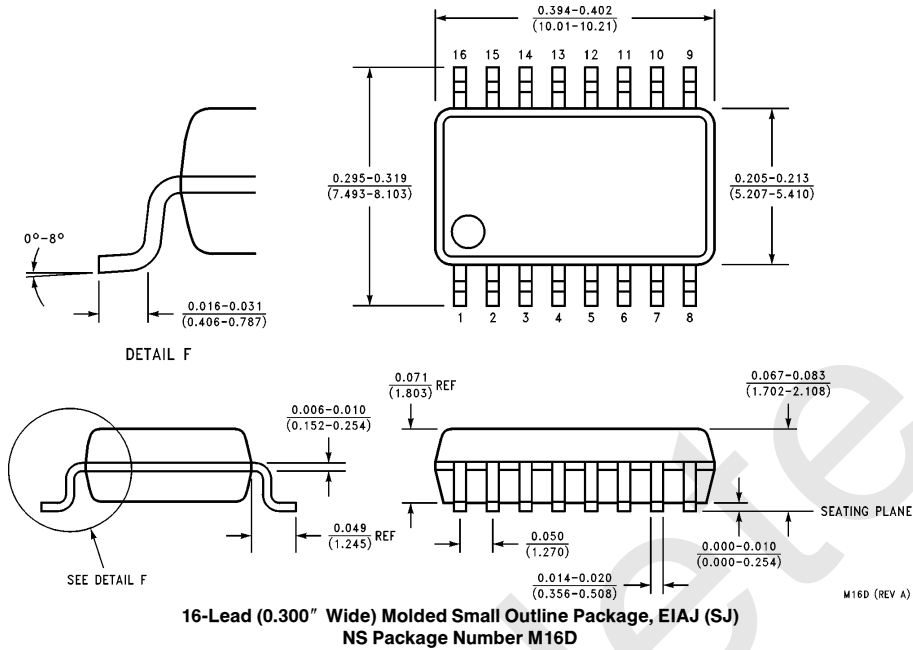


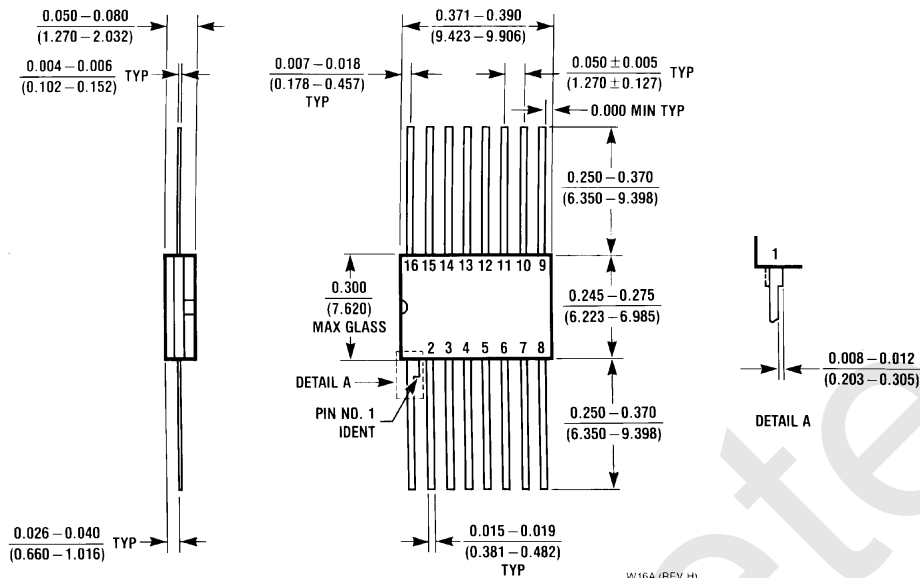
16-Lead Ceramic Dual-In-Line Package (D)
NS Package Number J16A



16-Lead (0.150" Wide) Molded Small Outline Package, JEDEC (S)
NS Package Number M16A

Physical Dimensions inches (millimeters) (Continued)



Physical Dimensions inches (millimeters) (Continued)

16-Lead Ceramic Flatpak (F)
NS Package Number W16A

LIFE SUPPORT POLICY

NATIONAL'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF NATIONAL SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.



National Semiconductor Corporation
2900 Semiconductor Drive
P.O. Box 58090
Santa Clara, CA 95052-8090
Tel: (408) 272-9959
TWX: (910) 339-9240

National Semiconductor GmbH
Livny-Gargan-Str. 10
D-82256 Fürstentfeldbruck
Germany
Tel: (81-41) 35-0
Telex: 527849
Fax: (81-41) 35-1

National Semiconductor Japan Ltd.
Sumitomo Chemical
Engineering Center
Bldg. 7F
1-7-1, Nakase, Mihamu-Ku
Chiba-City,
Chiba Prefecture 261
Tel: (043) 299-2300
Fax: (043) 299-2500

National Semiconductor Hong Kong Ltd.
13th Floor, Straight Block,
Ocean Centre, 5 Canton Rd.
Tsimshatsui, Kowloon
Hong Kong
Tel: (852) 2737-1600
Fax: (852) 2736-9960

National Semicondutores Do Brazil Ltda.
Rue Deputado Lacorda Franco
120-3A
Sao Paulo-SP
Brazil 05418-000
Tel: (55-11) 212-5066
Telex: 391-1131931 NSBR BR
Fax: (55-11) 212-1181

National Semiconductor (Australia) Pty. Ltd.
Building 16
Business Park Drive
Monash Business Park
Nottingham, Melbourne
Victoria 3168 Australia
Tel: (3) 558-9999
Fax: (3) 558-9998

National does not assume any responsibility for use of any circuitry described, no circuit patent licenses are implied and National reserves the right at any time without notice to change said circuitry and specifications.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Mobile Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Transportation and Automotive	www.ti.com/automotive
Video and Imaging	www.ti.com/video

TI E2E Community Home Page

e2e.ti.com

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2011, Texas Instruments Incorporated